

# SIGPRO's SoC Chip, the heart of 'All-in-one' PCDs.

*Flexium™ Emerges to be the Best Ever Communications Engine for Wireless Mobility Devices.*

## COMPANY

SIGPRO Wireless is a fabless semiconductor company engaged in the development of next generation System-on-Chip (SoC) hardware and embedded software solutions for Original Equipment Manufacturers (OEMs) involved in the development of wireless mobility terminals and networks capable of delivering integrated mobile communications, information, computation, navigation, and entertainment services.

Our flagship product Flexium™ is based on a unique and innovative architecture with unprecedented programmability. Flexium™ is a universal communication platform when used in a PCD will support (i) multiple Standards(2.5G, 3G), (ii) multiple data rates, (iii) multiple applications, and (iv) truly global roaming.

During 2002, SIGPRO's major focus is on (1) Product Commercialization, (2) Sales, and (3) Financing.

## We are **HIRING**...

- Senior Application Engineers
- Real-time SW Designer
- Senior Account Executives
- ASIC Test & Verification
- ASIC Designer-SoC Integration
- ASIC System Architect
- Senior System Engineers (Mobile Terminals)
- DSP Algorithm Specialist



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## PRODUCTS

SIGPRO's products and services portfolio includes:

- Flexium™ Chipset Product Line
- Software Product Line
- FlexCore™ IP Cores
- Development Platforms
- Design, Test, & Performance Tools (for OEMs)
- Design Support Services



# FLEXIUM™

Universal Communications  
Processor, the heart of  
tomorrow's 'all-in-one' PCDs.

SIGPRO launched its flagship Flexium™ chip in Europe in May 2002. A new breed of test, design, & evaluation boards will be ready to ship to customers in September.

## SALES

Since the launch of Flexium™ in Europe, SIGPRO has made significant advancements in sales activities. The prospects in Asia are even brighter.

- ▶ **June 2002** - After the successful Flexium™ product launch in Europe SIGPRO signed a Memorandum of Understanding (MoU) with a European manufacturer of mobile phones.
- ▶ **July 2002** - SIGPRO signed another Memorandum of Understanding (MoU) with a second European 3G hand held device manufacturer.
- ▶ **July 2002** - SIGPRO signs MoU with 3G partners in Asia.

SIGPRO's team is confident of signing more trial customers in Europe & Asia in the near future. Detailed discussions are well underway with several global PCD manufacturers.

## FINANCING

SIGPRO has been a hot favorite in many recent financing events. Some of these include:

- ▶ GoNorth Middle Stage Technology Financing, 21-22 Mar 2002, Montreal, Presentation
- ▶ ITFF 2002, 13-14 May 2002, Toronto, Presentation
- ▶ World Telecom Congress 2002, 25-26 Sep 2002, Paris, France, Presentation & Exhibition
- ▶ CSBA "Understanding the Wireless Universe", 16 May 2002, Stockholm, Sweden, Presentation



**Marketing Events:** Our recent marketing events include:

- ▶ CWTA Communications 2001, Toronto, 6-8 Nov 2001
- ▶ Wireless Industry Congress 2002, 26-27 Aug 2002, Ottawa - SIGPRO is the lead sponsor and organizer of WIC2002, Canada's second largest wireless conference and show. See [www.wic2002.com](http://www.wic2002.com).
- ▶ North American Product Launch, 26 Aug 2002, Ottawa at the WIC2002
- ▶ Asia Product Launch - SIGPRO Wireless will launch the Flexium™ product line in Asia this summer.

[www.sigprowireless.com](http://www.sigprowireless.com)